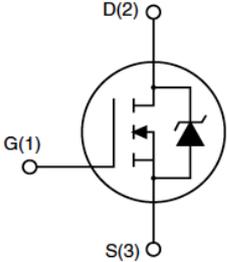


## Description

<p><b>Features</b></p> <ul style="list-style-type: none"> <li>● 500V, 20A</li> <li>● <math>R_{DS(ON)} = 0.25\Omega</math> (Typ.) @ <math>V_{GS} = 10V, I_D = 10A</math></li> <li>● Fast Switching</li> <li>● Improved dv/dt Capability</li> <li>● 100% Avalanche Tested</li> </ul>	<p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Switch Mode Power Supply(SMPS)</li> <li>● Uninterruptible Power Supply(UPS)</li> <li>● Power Factor Correction (PFC)</li> </ul>
 <p>TO-220F</p>	 <p>Schematic Diagram</p>

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Parameter	Max.	Units
V <sub>DSS</sub>	Drain-Source Voltage	500	V
V <sub>GSS</sub>	Gate-Source Voltage	±30	V
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 25°C	20
		T <sub>C</sub> = 100°C	12.5
I <sub>DM</sub>	Pulsed Drain Current <sup>note1</sup>	80	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>note2</sup>	1200	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C	45
R <sub>θJC</sub>	Thermal Resistance, Junction to Case	2.78	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	62.5	°C/W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	500	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=500V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 30V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note3</small>	$V_{GS}=10V, I_D=10A$	-	0.25	0.3	$\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1.0\text{MHz}$	-	2919	-	pF
$C_{oss}$	Output Capacitance		-	277	-	pF
$C_{riss}$	Reverse Transfer Capacitance		-	16	-	pF
$Q_g$	Total Gate Charge	$V_{DD}=400V, I_D=20A, V_{GS}=10V$	-	52	-	nC
$Q_{gs}$	Gate-Source Charge		-	12.6	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	18.6	-	nC
$g_{FS}$	Forward Transconductance	$V_{DS}=15V, I_D=10A$	-	18	-	S
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=250V, I_D=20A, R_G=10\Omega$	-	34	-	ns
$t_r$	Turn-on Rise Time		-	65	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	82	-	ns
$t_f$	Turn-off Fall Time		-	45	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	20	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	80	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_{SD}=20A$	-	-	1.5	V
$t_{rr}$	Reverse Recovery Time	$V_{GS}=0V, I_S=20A, di/dt=100A/\mu s$	-	535	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	5671	-	$\mu C$

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

 2.  $L=10\text{mH}, I_D=15.5A$ , Start  $T_J=25^\circ\text{C}$ 

 3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 1\%$

## Typical Performance Characteristics

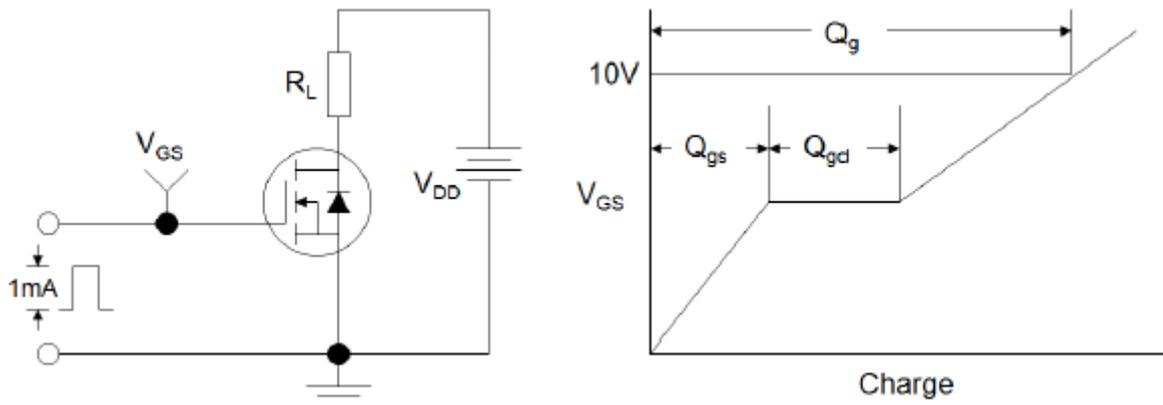


Figure1:Gate Charge Test Circuit & Waveform

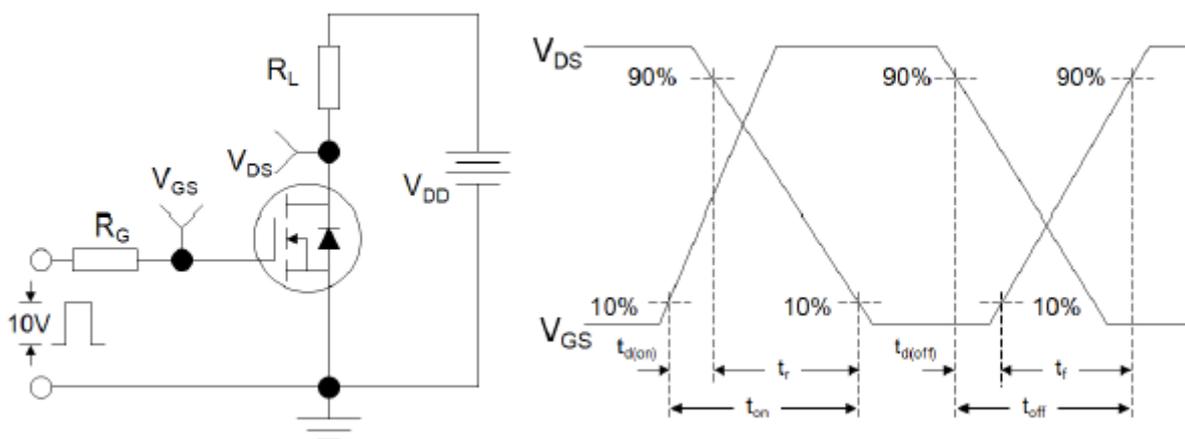


Figure 2: Resistive Switching Test Circuit & Waveforms

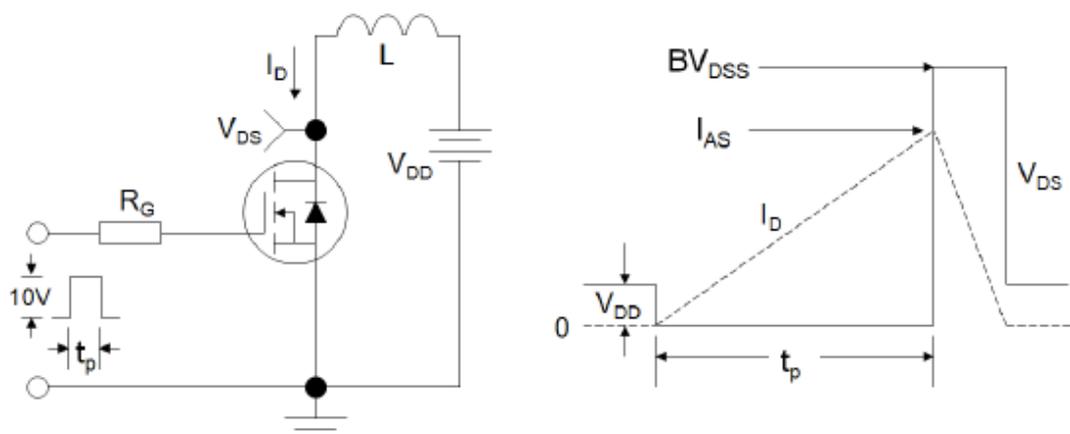
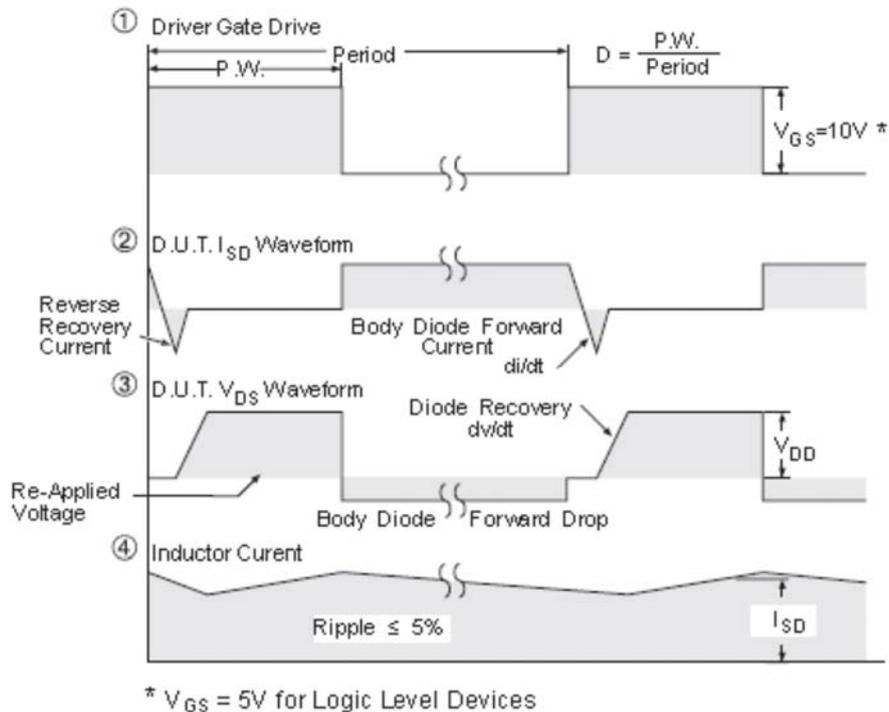
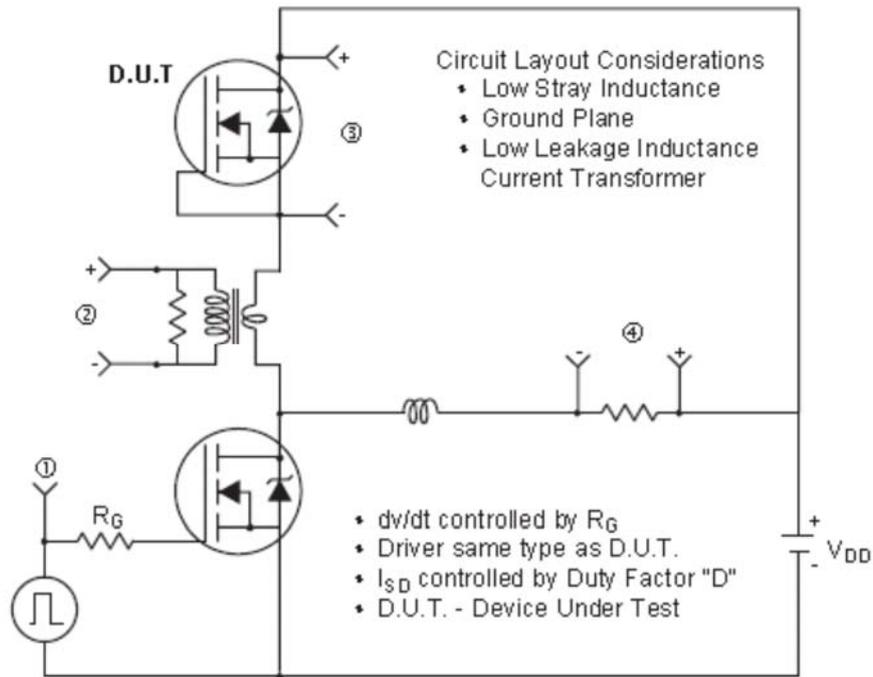


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms


**Figure 4: Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms (For N-channel)**